Small Signal MOSFET

20 V, 915 mA, Single N–Channel with ESD Protection, SC–75 and SC–89

Features

- Low R_{DS(on)} Improving System Efficiency
- Low Threshold Voltage, 1.5 V Rated
- ESD Protected Gate
- NV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC–Q101 Qualified and PPAP Capable
- Pb–Free Packages are Available

Applications

- Load/Power Switches
- Power Supply Converter Circuits
- Battery Management
- Portables like Cell Phones, PDAs, Digital Cameras, Pagers, etc.

MAXIMUM RATINGS (T_J = 25° C unless otherwise stated)

Paramet	Symbol	Value	Units		
Drain-to-Source Voltage			V _{DSS}	20	V
Gate-to-Source Voltage			V _{GS}	±6.0	V
Continuous Drain	$\begin{array}{c} \text{Steady} \\ \text{State} \end{array} \frac{\text{T}_{\text{A}} = 25^{\circ}\text{C}}{\text{T}_{\text{A}} = 85^{\circ}\text{C}} \end{array}$		I _D	915	mA
Current (Note 1)				660	
Power Dissipation (Note 1)	Stea	dy State	PD	300	mW
Pulsed Drain Current t _p =10 μs			I _{DM}	1.3	А
Operating Junction and Storage Temperature			T _J , T _{STG}	–55 to 150	°C
Continuous Source Current (Body Diode)			I _S	280	mA
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)			ΤL	260	°C

THERMAL RESISTANCE RATINGS

Parameter	Symbol	Value	Units
Junction-to-Ambient - Steady State (Note 1) SC-75 / SOT-416 SC-89	$R_{ hetaJA}$	416 400	°C/W

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

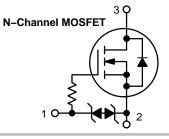
1. Surface mounted on FR4 board using 1 in sq pad size (Cu area = 1.127 in sq [1 oz] including traces).



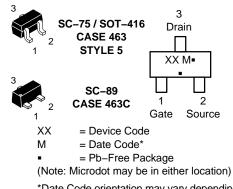
ON Semiconductor®

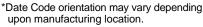
http://onsemi.com

V _{(BR)DSS}	R _{DS(on)} TYP	I _D MAX
20 V	0.127 Ω @ 4.5 V	
	0.170 Ω @ 2.5 V	915 mA
	0.242 Ω @ 1.8 V	01011/
	0.500 Ω @ 1.5 V	

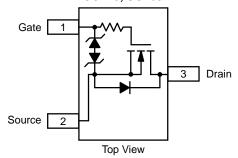


MARKING DIAGRAM & PIN ASSIGNMENT









ORDERING INFORMATION

See detailed ordering and shipping information on page 4 of this data sheet.

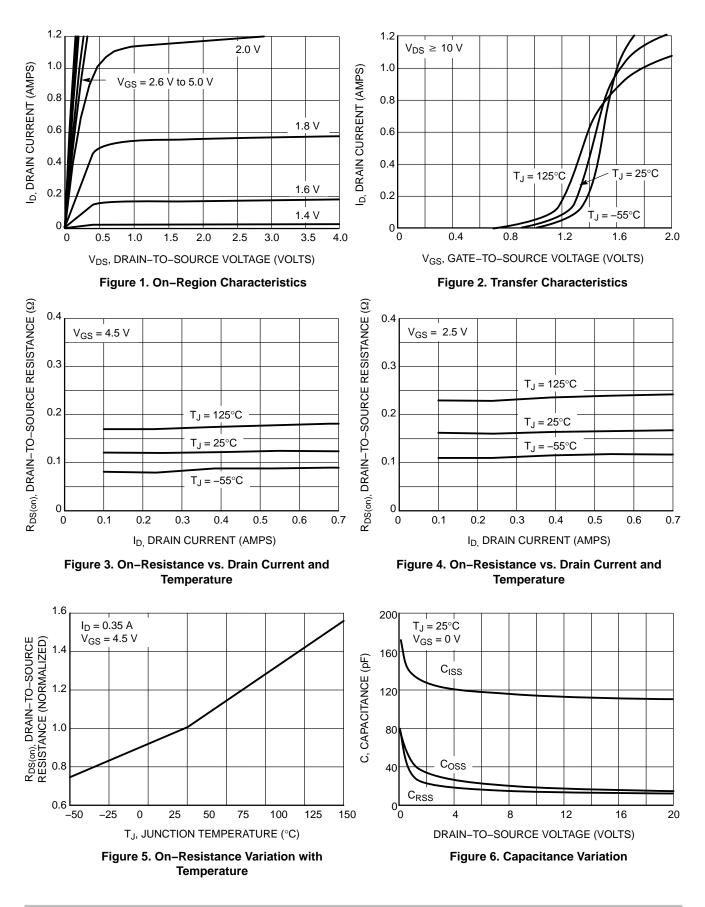
ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise stated)

Parameter	Symbol	Test Condition		Min	Тур	Max	Unit
OFF CHARACTERISTICS							
Drain-to-Source Breakdown Voltage	V _{(BR)DSS} V _{GS} = 0 V, I _D = 250 μA 20		20	26		V	
Drain-to-Source Breakdown Voltage Temperature Coefficient	V _{(BR)DSS} /T _J				18.4		mV/°C
Zero Gate Voltage Drain Current	I _{DSS}	$V_{GS} = 0 V, V_{D}$	_{DS} = 16 V			100	nA
Gate-to-Source Leakage Current	I _{GSS}	$V_{DS} = 0 V, V_{GS}$	_S = ±4.5 V			±1.0	μΑ
ON CHARACTERISTICS (Note 2)							
Gate Threshold Voltage	V _{GS(TH)}	$V_{GS} = V_{DS}, I_D$	= 250 μA	0.45	0.76	1.1	V
Negative Threshold Temperature Coefficient	V _{GS(TH)} /T _J				-2.15		mV/°C
Drain-to-Source On Resistance	R _{DS(on)}	V_{GS} = 4.5 V, I _D	= 600 mA		127	230	mΩ
		V_{GS} = 2.5 V, I _D	= 500 mA		170	275	-
		V _{GS} = 1.8 V, I _D	= 350 mA		242	700	
		V_{GS} = 1.5 V, I _D = 40 mA			500	950	
Forward Transconductance	g fs	V _{DS} = 10 V, I _D = 400 mA			1.4		S
CHARGES AND CAPACITANCES							
Input Capacitance	C _{ISS}				110		pF
Output Capacitance	C _{OSS}	V _{GS} = 0 V, f = V _{DS} = 1			16		7
Reverse Transfer Capacitance	C _{RSS}	50			12		
Total Gate Charge	Q _{G(TOT)}				1.82		nC
Threshold Gate Charge	Q _{G(TH)}	V _{GS} = 4.5 V, V _I	_{DS} = 10 V,		0.2		
Gate-to-Source Charge	Q _{GS}	$I_{\rm D} = 0.2$	Ä		0.3		7
Gate-to-Drain Charge	Q _{GD}		Γ		0.42		
SWITCHING CHARACTERISTICS (No	te 3)						
Turn–On Delay Time	t _{d(ON)}				3.7		ns
Rise Time	t _r	V_{GS} = 4.5 V, V_{DD} = 10 V, I _D = 0.2 A, R _G = 10 Ω			4.4		7
Turn–Off Delay Time	t _{d(OFF)}				25		
Fall Time	t _f				7.6		
DRAIN-SOURCE DIODE CHARACTE	RISTICS				-	-	•
Forward Diode Voltage	V _{SD}	V _{GS} = 0 V,	$T_J = 25^{\circ}C$		0.67	1.1	V
	$I_{\rm S} = 200 \rm{mA}$		T _J = 125°C		0.54		1

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 2. Pulse Test: pulse width \leq 300 µs, duty cycle \leq 2%.

3. Switching characteristics are independent of operating junction temperatures.

TYPICAL ELECTRICAL CHARACTERISTICS



TYPICAL ELECTRICAL CHARACTERISTICS

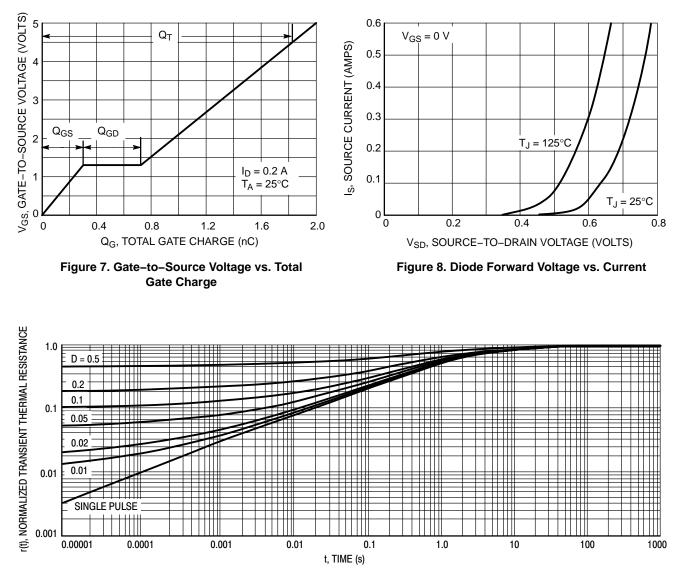


Figure 9. Normalized Thermal Response

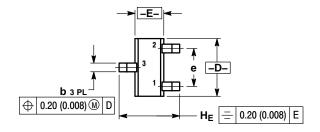
ORDERING INFORMATION

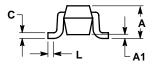
Device	Device Marking Pack		Shipping [†]
NTA4153NT1	TR	SC-75 / SOT-416	3000 / Tape & Reel
NTA4153NT1G	TR	SC-75 / SOT-416 (Pb-Free)	3000 / Tape & Reel
NTE4153NT1G	TP	SC-89 (Pb-Free)	3000 / Tape & Reel
NVA4153NT1G	VR	SC-75 / SOT-416 (Pb-Free)	3000 / Tape & Reel
NVE4153NT1G	VP	SC-89 (Pb-Free)	3000 / Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS

SC-75/SOT-416 **CASE 463** ISSUE F





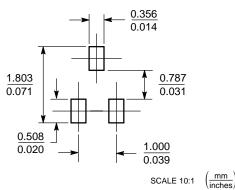
NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. - CONTROLLING DIMENSION: MILLIMETER.

2.	CONTROLLING	DIMENSION:	MILLIMETER.

	MILLIMETERS			INCHES			
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
Α	0.70	0.80	0.90	0.027	0.031	0.035	
A1	0.00	0.05	0.10	0.000	0.002	0.004	
b	0.15	0.20	0.30	0.006	0.008	0.012	
С	0.10	0.15	0.25	0.004	0.006	0.010	
D	1.55	1.60	1.65	0.059	0.063	0.067	
E	0.70	0.80	0.90	0.027	0.031	0.035	
е	1.00 BSC			0	.04 BSC		
L	0.10	0.15	0.20	0.004	0.006	0.008	
HE	1.50	1.60	1.70	0.061	0.063	0.065	

STYLE 5: PIN 1. GATE 2. SOURCE 3. DRAIN

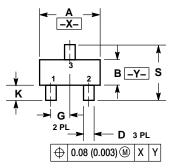
SOLDERING FOOTPRINT*



*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

SC-89 CASE 463C-03 ISSUE C

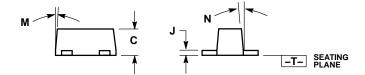


NOTES:

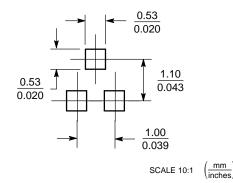
- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 CONTROLLING DIMENSION: MILLIMETERS
- CONTROLLING DIMENSION: MILLIMETERS
 MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE

MATERIAL. 4. 463C-01 OBSOLETE, NEW STANDARD 463C-02.

	MILLIMETERS			INCHES			
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
Α	1.50	1.60	1.70	0.059	0.063	0.067	
В	0.75	0.85	0.95	0.030	0.034	0.040	
С	0.60	0.70	0.80	0.024	0.028	0.031	
D	0.23	0.28	0.33	0.009	0.011	0.013	
G	0.50 BSC			0.020 BSC			
н	C	.53 REF	-	0.021 REF			
J	0.10	0.15	0.20	0.004	0.006	0.008	
ĸ	0.30	0.40	0.50	0.012	0.016	0.020	
L	1	.10 REF	-	0.043 REF			
М			10 °			10 °	
Ν			10 °			10 °	
S	1.50	1.60	1.70	0.059	0.063	0.067	



SOLDERING FOOTPRINT*



*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor P.O. Box 5163, Denver, Colorado 80217 USA Phone: 303–675–2175 or 800–344–3860 Toll Free USA/Canada Fax: 303–675–2176 or 800–344–3867 Toll Free USA/Canada Email: orderlit@onsemi.com N. American Technical Support: 800–282–9855 Toll Free USA/Canada Europe, Middle East and Africa Technical Support:

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